

REVISION				
No.	DESCRIPTION	DRAWN	APPR	DATE
1	Initial Registration	S.Y.EUN	I.C.KIM	2019. 09. 17.

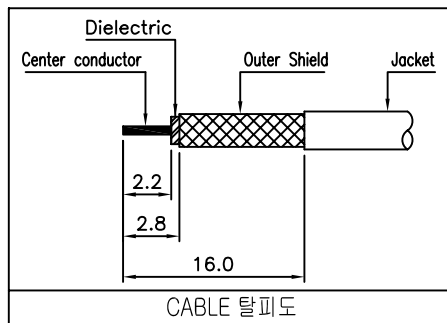
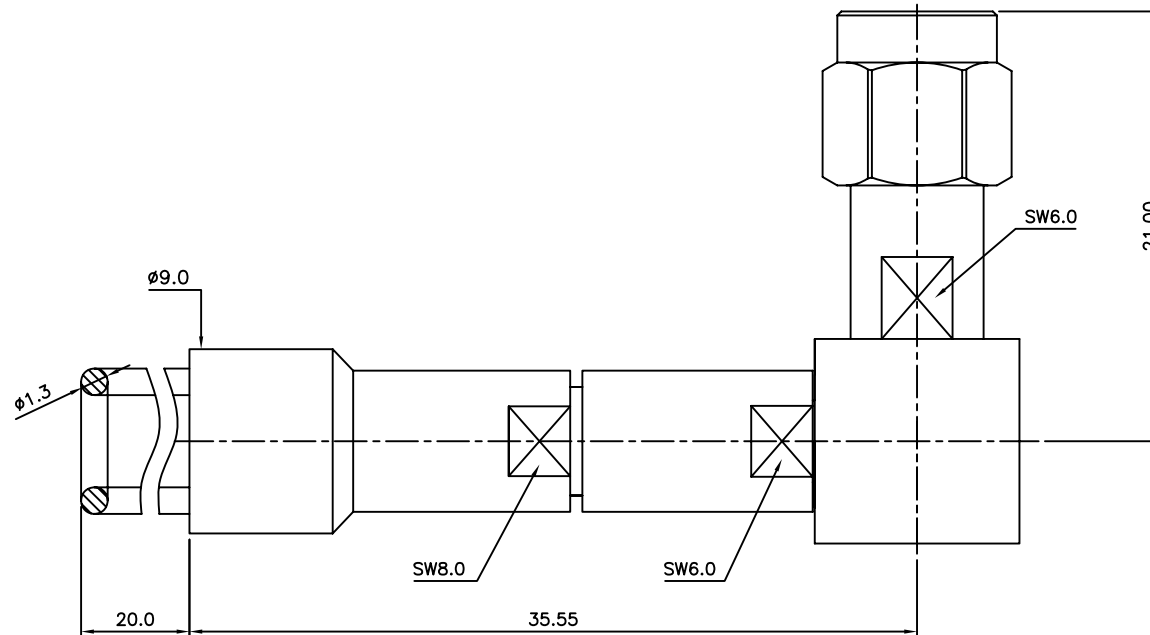
ELECTRICAL DATA

1. IMPEDANCE : 50ohm
2. FREQUENCY RANGE : DC~40GHz
3. VSWR (Max) : 1.35

Mate compatible table	
SMA [~18GHz]	Mate
3.5mm [~26.5GHz]	
2.92mm(K) [~40GHz]	
2.4mm [~50GHz]	Mate
1.85mm(V) [~65GHz]	

15	SPRING	1	SUS	Passivated	DSR01176-5/1
14	CLAMP	1	MBsBD C3604BD-F	Nickel Plate	DBN00217-5/1
13	CABLE INSERT	1	MBsBD C3604BD-F	Gold Plate	DIS00282-5/2
12	COUPLING CAP	1	SUS303	Passivated	DCU00006-5/1
11	C-RING	1	SUS303	부동태 처리	DSR00002-5/1
10	INSULATOR	1	PEEK		DIN03042-N/1
9	INSULATOR	2	PEEK		DIN02996-N/3
8	CONTACT (C)	1	MBsBD C3604BD-F	Gold Plate (1μm)	DCT03993-5/4
7	CONTACT (B)	1	BeCu C17300	Gold Plate (1μm)	DCT03992-5/7
6	CONTACT (A)	1	BeCu C17300	Gold Plate (1μm)	DCT04026-5/3
5	INSERT (B)	1	SUS303	Passivated	DIS00294-5/3
4	INSERT (A)	1	SUS303	Passivated	DIS00298-5/2
3	BODY (C)	1	SUS303	Passivated	DBD04461-5/2
2	BODY (B)	1	SUS303	Passivated	DBD04506-5/1
1	BODY (A)	1	MBsBD C3604BD-F	SUCO Plate (1~1.5μm)	DBD04459-5/3

NO.	DESCRIPTION	Q'TY	VENDER	PART NO.	RAMARKS
DATE 2019. 9. 17.					
APPROVED BY I.C.KIM					
CHECKED BY					
DRAWN BY S.Y.EUN					
CHECKED BY					
SCALE 4/1 UNIT mm					
TITLE 2.92mm CABLE PL MUA165SD					
A3 DWG NO. CN03845-7/2					
REVISION I R SHEET 1 of 1					



* 조립방법 *

1. ⑥+⑨+④+②번 부품들을 정해진 JIG를 이용하여 조립한다. (조립품 1)
2. ⑦+⑨+⑤+③번 부품들을 정해진 JIG를 이용하여 조립한다. (조립품 2)
3. ⑧+⑩번 부품을 조립하여 ①번 BODY에 끼워넣어 조립한다. (조립품 3)
4. 조립품 3에 조립품 1, 조립품 2 부품들을 조립한다.(도면 형사 참조)
5. ⑪C-RING, ⑫CAP 부품을 도면과 같이 조립한다.
6. ⑭, ⑮번은 케이블에 끼워넣기전 납땜을 하여 고정 시킨 후 조립한다.

TOLERANCE	Decimal
	±0.2
MATERIAL	Angle
	±1°
FINISH	UNIT
	mm

